

**MOSFET – Power, N-Channel,
SUPERFET III, Easy Drive****650 V, 10 A, 360 mΩ****FCP360N65S3R0****Description**

SUPERFET III MOSFET is onsemi's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III MOSFET Easy drive series helps manage EMI issues and allows for easier design implementation.

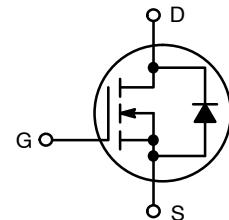
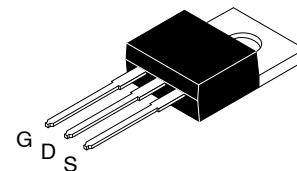
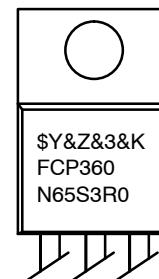
Features

- 700 V @ $T_J = 150^\circ\text{C}$
- Typ. $R_{DS(on)} = 310 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. $Q_g = 18 \text{ nC}$)
- Low Effective Output Capacitance (Typ. $C_{oss(\text{eff.})} = 173 \text{ pF}$)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

Applications

- Computing / Display Power Supplies
- Telecom / Server Power Supplies
- Industrial Power Supplies
- Lighting / Charger / Adapter

V_{DSS}	$R_{DS(\text{ON}) \text{ MAX}}$	$I_D \text{ MAX}$
650 V	360 mΩ @ 10 V	10 A

**N-Channel MOSFET****TO-220-3LD
CASE 340AT****MARKING DIAGRAM**

\$Y = onsemi Logo
 &Z = Assembly Plant Code
 &3 = Numeric Date Code
 &K = Lot Code
 FCP360N65S3R0 = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

FCP360N65S3R0

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C, Unless otherwise specified)

Symbol	Parameter		Value	Unit
V _{DSS}	Drain to Source Voltage		650	V
V _{GSS}	Gate to Source Voltage	DC	±30	V
		AC (f > 1 Hz)	±30	V
I _D	Drain Current	Continuous (T _C = 25°C)	10	A
		Continuous (T _C = 100°C)	6	
I _{DM}	Drain Current	Pulsed (Note 1)	25	A
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		40	mJ
I _{AS}	Avalanche Current (Note 1)		2.1	A
E _{AR}	Repetitive Avalanche Energy (Note 1)		0.83	mJ
dv/dt	MOSFET dv/dt		100	V/ns
	Peak Diode Recovery dv/dt (Note 3)		20	
P _D	Power Dissipation	(T _C = 25°C)	83	W
		Derate Above 25°C	0.67	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		−55 to +150	°C
T _L	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 s		300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Repetitive rating: pulse-width limited by maximum junction temperature.
2. I_{AS} = 2.1 A, R_G = 25 Ω, starting T_J = 25°C.
3. I_{SD} ≤ 5 A, di/dt ≤ 200 A/μs, V_{DD} ≤ 400 V, starting T_J = 25°C.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
R _{θJC}	Thermal Resistance, Junction to Case, Max.	1.5	°C/W
R _{θJA}	Thermal Resistance, Junction to Ambient, Max.	62.5	

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
FCP360N65S3R0	FCP360N65S3R0	TO-220	Tube	N/A	N/A	50 Units

FCP360N65S3R0

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

BV _{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}, T_J = 25^\circ\text{C}$	650	–	–	V
		$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}, T_J = 150^\circ\text{C}$	700	–	–	V
$\Delta V_{DSS}/\Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 1 \text{ mA}$, Referenced to 25°C	–	0.68	–	$^\circ\text{C}$
Id _{SS}	Zero Gate Voltage Drain Current	$V_{DS} = 650 \text{ V}, V_{GS} = 0 \text{ V}$	–	–	1	μA
		$V_{DS} = 520 \text{ V}, T_C = 125^\circ\text{C}$	–	0.58	–	
I _{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	–	–	± 100	nA

ON CHARACTERISTICS

$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 0.2 \text{ mA}$	2.5	–	4.5	V
$R_{DS(\text{on})}$	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$	–	310	360	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS} = 20 \text{ V}, I_D = 5 \text{ A}$	–	6	–	S

DYNAMIC CHARACTERISTICS

C_{iss}	Input Capacitance	$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	–	730	–	pF
C_{oss}	Output Capacitance		–	15	–	pF
$C_{oss(\text{eff.})}$	Effective Output Capacitance	$V_{DS} = 0 \text{ V to } 400 \text{ V}, V_{GS} = 0 \text{ V}$	–	173	–	pF
$C_{oss(\text{er.})}$	Energy Related Output Capacitance	$V_{DS} = 0 \text{ V to } 400 \text{ V}, V_{GS} = 0 \text{ V}$	–	26	–	pF
$Q_{g(\text{tot})}$	Total Gate Charge at 10 V	$V_{DS} = 400 \text{ V}, I_D = 5 \text{ A}, V_{GS} = 10 \text{ V}$ (Note 4)	–	18	–	nC
	Gate to Source Gate Charge		–	4.3	–	nC
	Gate to Drain "Miller" Charge		–	7.6	–	nC
ESR	Equivalent Series Resistance	$f = 1 \text{ MHz}$	–	1	–	Ω

SWITCHING CHARACTERISTICS

$t_{d(\text{on})}$	Turn-On Delay Time	$V_{DD} = 400 \text{ V}, I_D = 5 \text{ A},$ $V_{GS} = 10 \text{ V}, R_g = 4.7 \Omega$ (Note 4)	–	12	–	ns
t_r	Turn-On Rise Time		–	11	–	ns
$t_{d(\text{off})}$	Turn-Off Delay Time		–	34	–	ns
t_f	Turn-Off Fall Time		–	10	–	ns

SOURCE-DRAIN DIODE CHARACTERISTICS

I_S	Maximum Continuous Source to Drain Diode Forward Current	–	–	10	A	
I_{SM}	Maximum Pulsed Source to Drain Diode Forward Current	–	–	25	A	
V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{SD} = 5 \text{ A}$	–	–	1.2	V
t_{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{SD} = 5 \text{ A},$ $dI_F/dt = 100 \text{ A}/\mu\text{s}$	–	241	–	ns
Q_{rr}	Reverse Recovery Charge		–	2.4	–	μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

TYPICAL PERFORMANCE CHARACTERISTICS

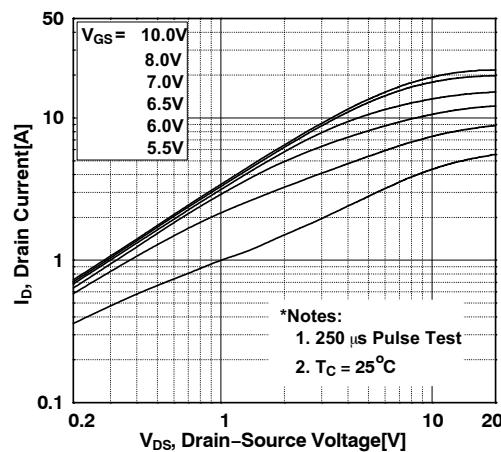


Figure 1. On-Region Characteristics

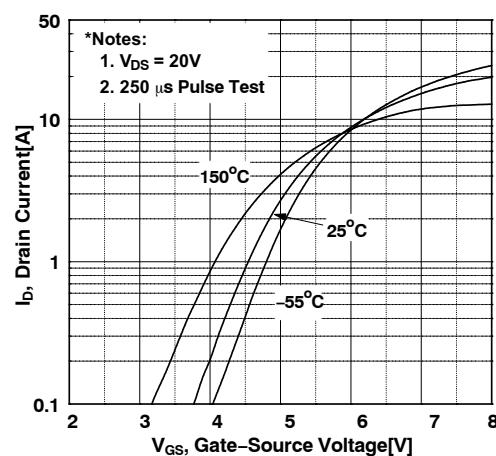


Figure 2. Transfer Characteristics

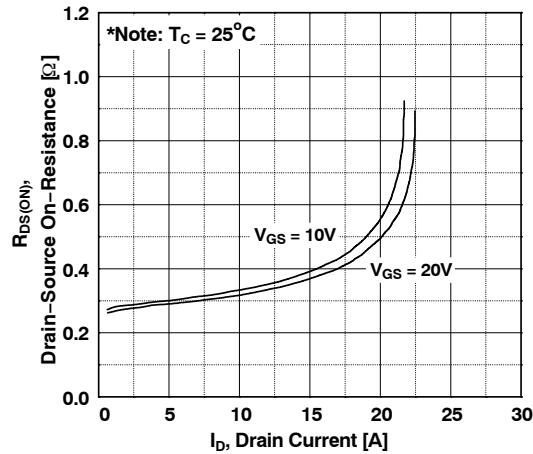


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

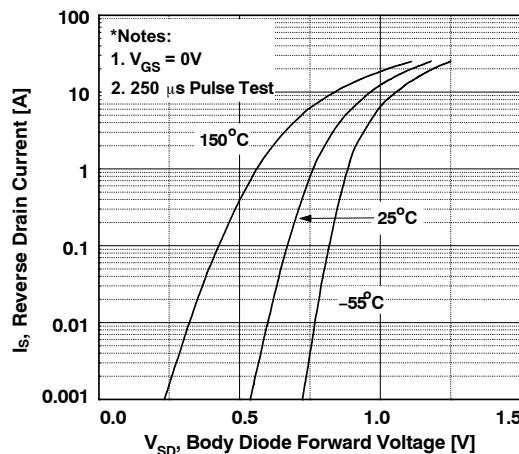


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

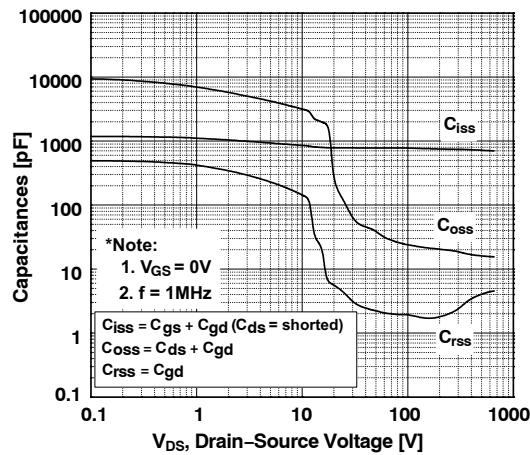


Figure 5. Capacitance Characteristics

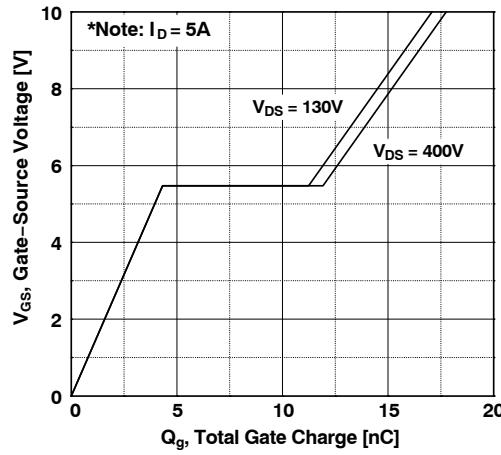


Figure 6. Gate Charge Characteristics

TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

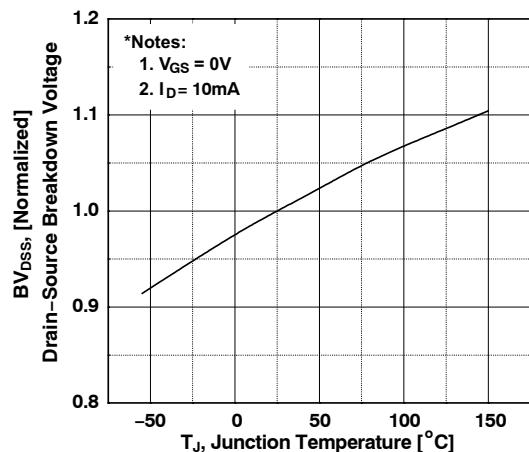


Figure 7. Breakdown Voltage Variation vs. Temperature

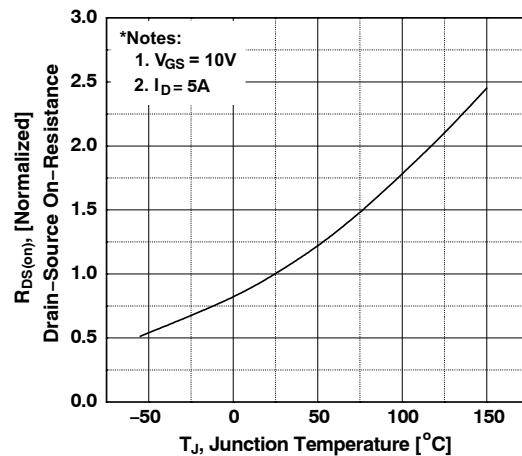


Figure 8. On-Resistance Variant vs. Temperature

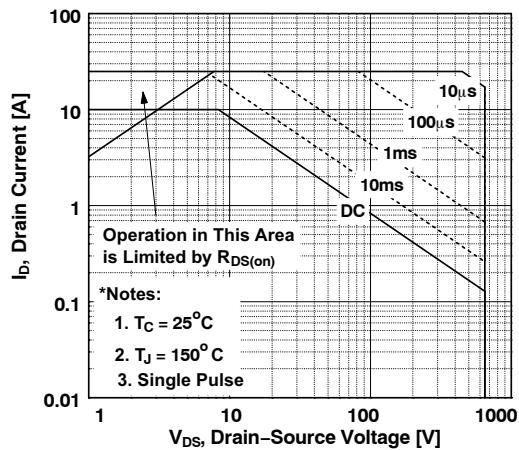


Figure 9. Maximum Safe Operation Area

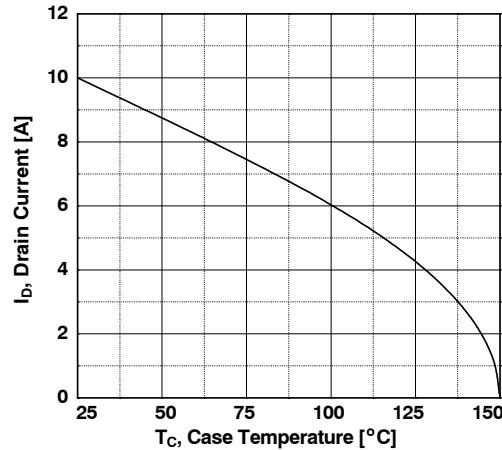
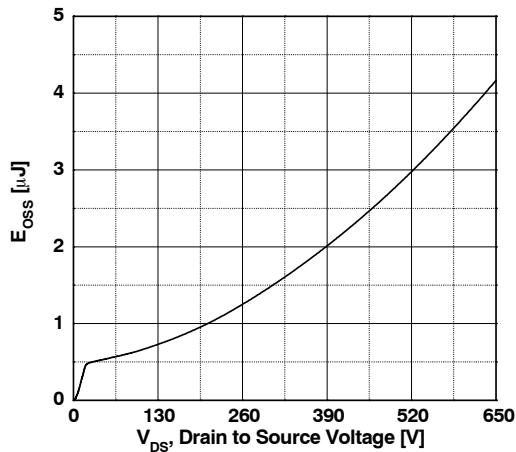


Figure 10. Maximum Drain Current vs. Case Temperature

Figure 11. E_{OSS} vs. Drain to Source Voltage

TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

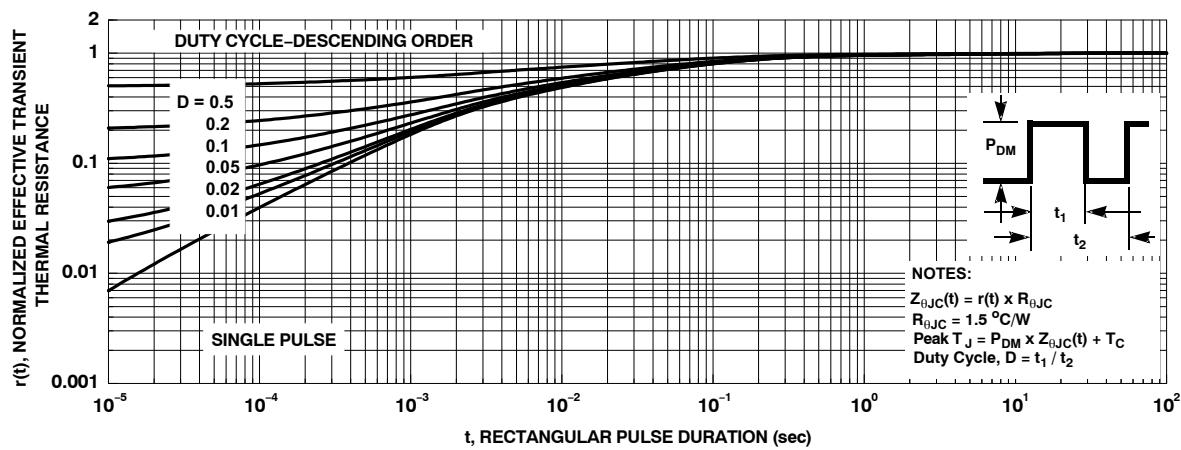


Figure 12. Transient Thermal Response Curve

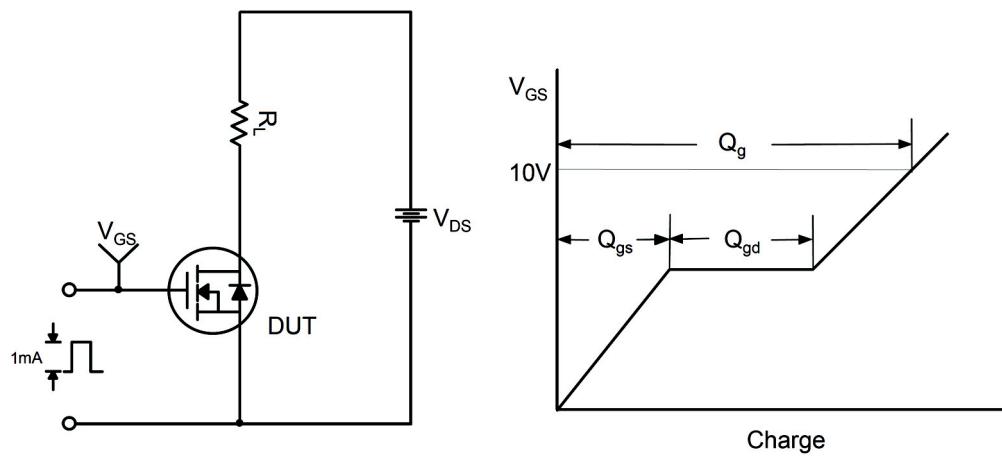


Figure 13. Gate Charge Test Circuit & Waveform

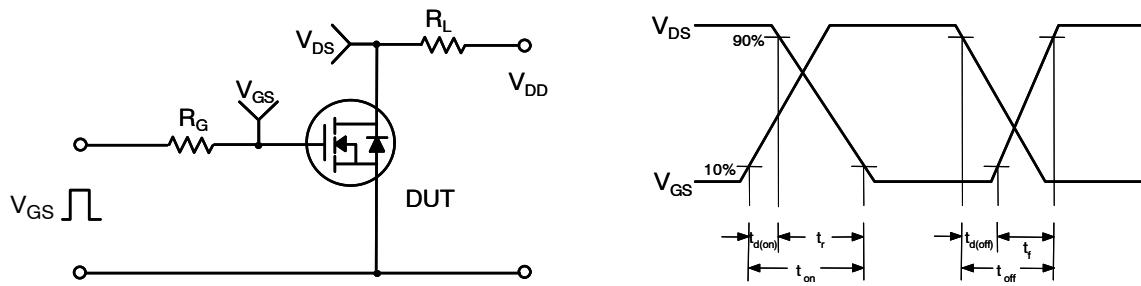


Figure 14. Resistive Switching Test Circuit & Waveforms

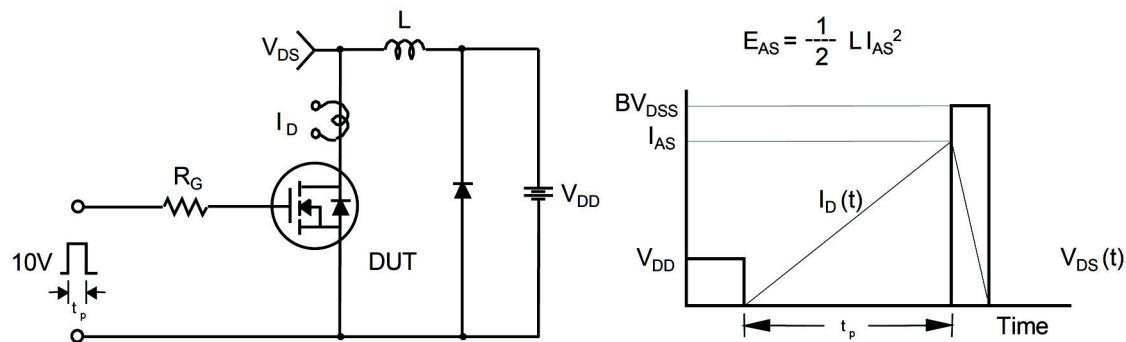


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

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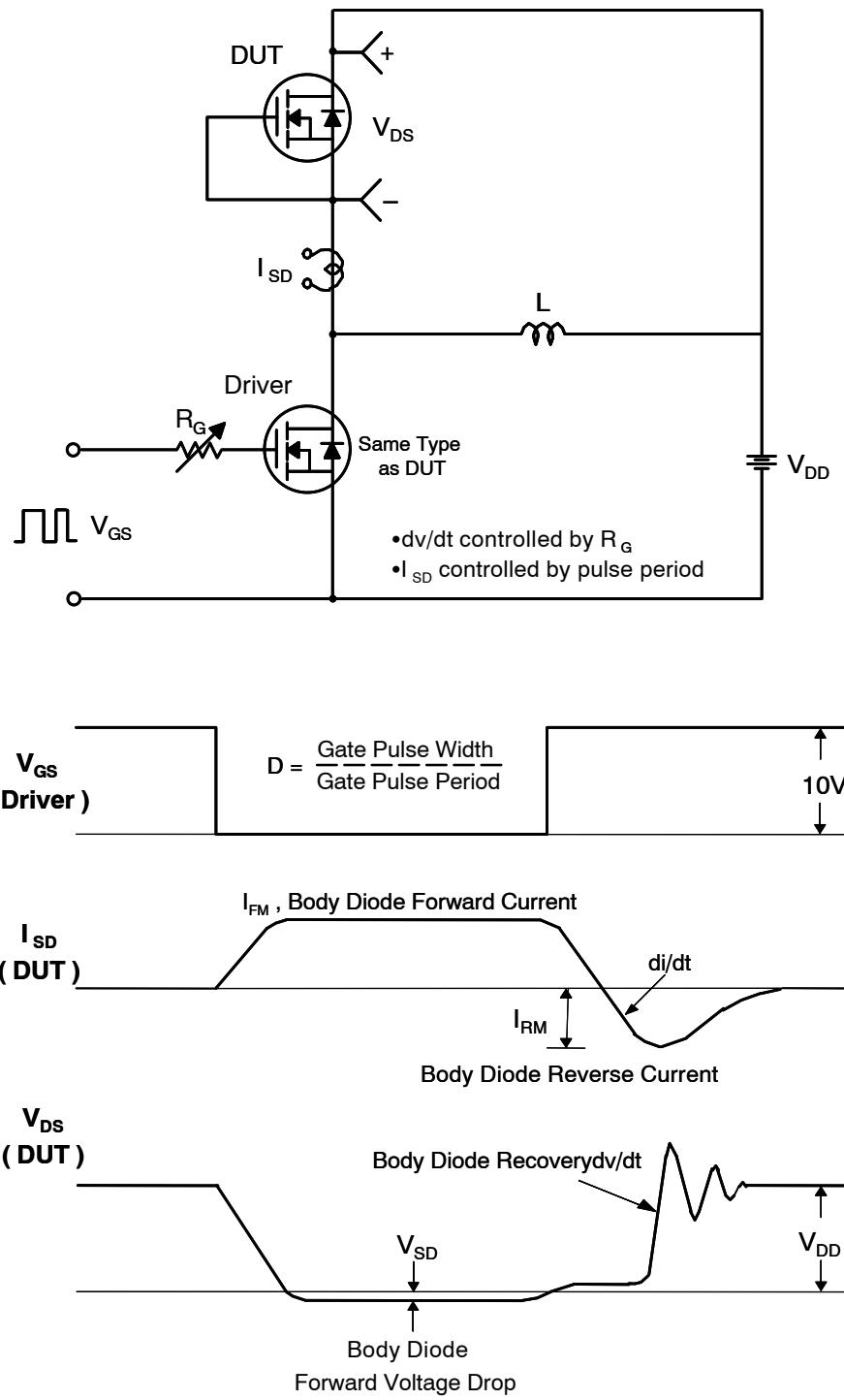
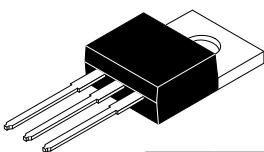


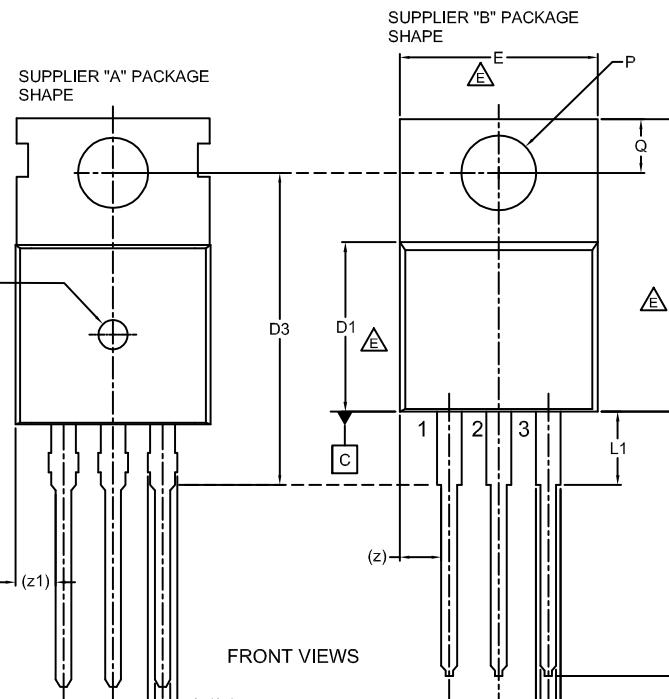
Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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TO-220-3LD
CASE 340AT
ISSUE B

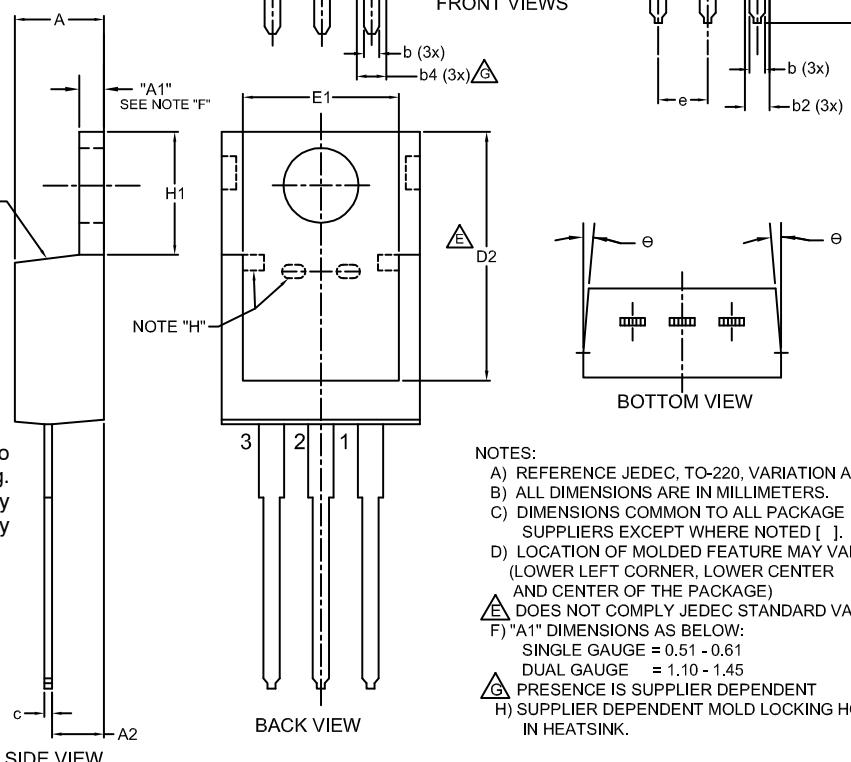
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DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	4.00	--	4.70
A1	SEE NOTE "F"		
A2	2.10	--	2.85
b	0.55	--	1.00
b2	1.10	--	1.62
b4	1.42	--	1.62
c	0.36	--	0.60
D	13.90	--	16.30
D1	8.13	--	9.40
D2	11.50	--	14.30
D3	15.42	--	16.51
E	9.65	--	10.67
E1	7.59	--	8.65
e	2.40	--	2.67
H1	6.06	--	6.69
L	12.70	--	14.04
L1	2.70	--	4.10
P	3.50	--	4.00
Q	2.50	--	3.40
z	2.13 REF		
z1	2.06 REF		
Θ	3°	—	5°

GENERIC
MARKING DIAGRAM*

XXXXX
XXXXX
AYWWZZ

XXXX = Specific Device Code
 A = Assembly Location
 Y = Year
 WW = Work Week
 ZZ = Assembly Lot Code



*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

NOTES:

- A) REFERENCE JEDEC, TO-220, VARIATION AB
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS COMMON TO ALL PACKAGE SUPPLIERS EXCEPT WHERE NOTED [].
- D) LOCATION OF MOLDED FEATURE MAY VARY (LOWER LEFT CORNER, LOWER CENTER AND CENTER OF THE PACKAGE).
- △ DOES NOT COMPLY JEDEC STANDARD VALUE.
- F) "A1" DIMENSIONS AS BELOW:
 - SINGLE GAUGE = 0.51 - 0.61
 - DUAL GAUGE = 1.10 - 1.45
- △ PRESENCE IS SUPPLIER DEPENDENT
- H) SUPPLIER DEPENDENT MOLD LOCKING HOLES IN HEATSINK.

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